

Title (en)  
GRAVURE CYLINDER-USE COPPER PLATING METHOD AND DEVICE

Title (de)  
VERKUPFERUNGSVERFAHREN UND -VORRICHTUNG FÜR TIEFDRUCKZYLINDER

Title (fr)  
PROCEDE ET DISPOSITIF DE CUIVRAGE DE CYLINDRE DE GRAVURE

Publication  
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Application  
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Abstract (en)  
The present invention provides a copper plating method and apparatus for a gravure cylinder in which copper plating with more uniform thickness can be provided over a full length of a gravure cylinder without causing defects such as rashes and pits irrespective of a size of the gravure cylinder, concentration of a copper plating solution can be managed automatically, a consumption amount of an additive is reduced to make it possible to perform a plating treatment within a short period of time, a power supply cost is reduced, and handling is easy with excellent visibility. A gravure cylinder in a hollow cylindrical shape is held at both ends in a longitudinal direction. The gravure cylinder is accommodated in a plating bath filled with a copper plating solution. The gravure cylinder is energized so that the gravure cylinder functions as a cathode while being rotated at a predetermined speed. A pair of anode chambers in a long box shape, in which insoluble anodes are provided upright slidably to both sides of the gravure cylinder in the plating bath and energized so as to function as an anode, are brought close to both side surfaces of the gravure cylinder at a predetermined interval. Copper plating is provided on an outer peripheral surface of the gravure cylinder.

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